Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**.0145”**



**.0145”**

**Top Material: Al**

**Backside Material: Au**

**Bond Pad Size: .004 X .004”**

**Backside Potential: COLLECTOR**

**Mask Ref:**

**APPROVED BY: MG DIE SIZE : .0145 X .0145” DATE: 11/10/21**

**MFG: CENTRAL SEMI THICKNESS: P/N: 2N918**

**DG 10.1.2**

#### Rev B, 7/19/02